

Material Declaration Report

Package Type:	TQFN 48L
Pericom Package Code:	ZD48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
REACH Compliance:	Yes
Halogen Free:	Yes

Component Weight (mg):	88.500
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	5/24/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	42.300	ASEM	Silica Fused	60676-86-0	93.700	39.635
			Epoxy Resin	Trade Secret	3.000	1.269
			Phenol Resin	Trade Secret	3.000	1.269
			Carbon black	1333-86-4	0.300	0.127
		SPEL	Silica	60676-86-0	90.150	38.133
			Phenol resin	Proprietary	3.500	1.481
			Epoxy Resin-1	Proprietary	1.750	0.740
			Epoxy Resin-2	Proprietary	1.750	0.740
			Epoxy Resin-3	Proprietary	1.750	0.740
			Others Non-hazardous Material	Proprietary	1.000	0.423
		Carbon Black	1333-86-4	0.100	0.042	
LEADFRAME	40.100		Copper	7440-50-8	96.953	38.878
			Iron	7439-89-6	2.350	0.942
			Zinc	7440-66-6	0.111	0.044
			Phosphorus	7723-14-0	0.065	0.026
			Nickel	7440-02-0	0.473	0.190
			Palladium	7440-05-3	0.041	0.016
			Gold	7440-57-5	0.007	0.003
SILICON DIE	3.800		Silicon (Si)	7440-21-3	99.192	3.769
			Non-hazardous Metal	Proprietary	0.808	0.031
DIE ATTACH EPOXY	0.600	ASEM	Silver	7440-22-4	73.000	0.438
			Acrylic resin	Trade Secret	8.500	0.051
			Polybutadiene derivative	Trade Secret	5.500	0.033
			Butadiene copolymer	Trade Secret	2.000	0.012
			Epoxy resin	Trade Secret	2.500	0.015
			Acrylate	Trade Secret	5.500	0.033
			Peroxide	Trade Secret	1.000	0.006
		Additive	Trade Secret	2.000	0.012	
		SPEL	Silver	7440-22-4	80.000	0.480
			Epoxy Resin	9003-36-5	10.000	0.060
			Diluent	26447-14-3	6.000	0.036
			Dicyandiamide	461-58-5	0.500	0.003
			Hardener	620-92-8	3.500	0.021
GOLD WIRE	1.700		Gold(Au)	7440-57-5	99.990	1.700
			Impurities	-	0.010	0.000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table> <p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													